



Y O G I T E C H

Simplifying SIL3 MCU safety architectures
in automotive applications according to IEC61508 norm

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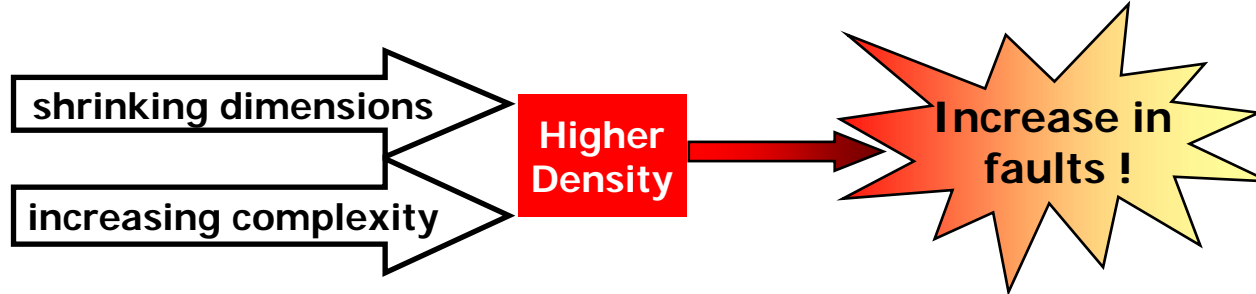
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Outline

- Background
- From black to white-box approach: the fRMethodology
- The faultRobust IPs
- A comprehensive approach
- Conclusions

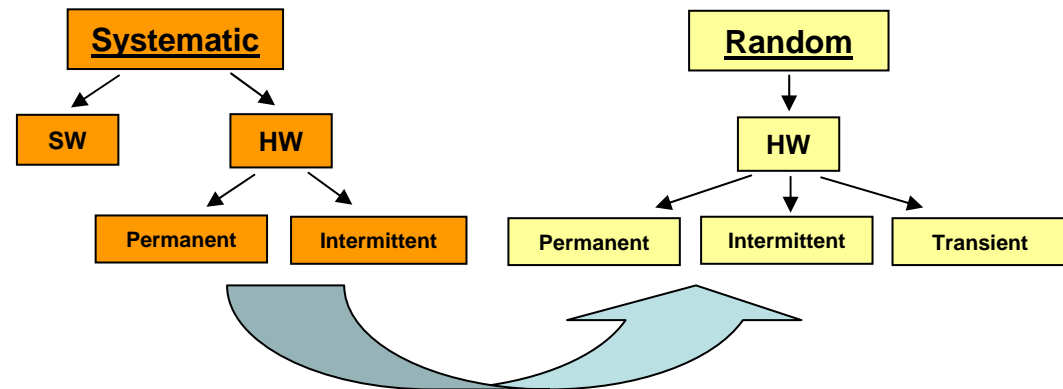
Background (1)

New technologies allow **deeper and deeper integration**

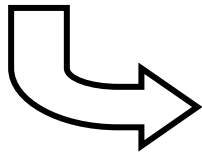


Fault model	Unit	Sources	Trend
Permanent	$\leq 10^{-5}$ FIT/gate	Telcordia Pauli, VDI SN29500	↔
Transient (memories)	$10^{-2} \div 10^{-4}$ FIT/bit	ITRS 2006	↔ ↑
Transient (registers)	$10^{-3} \div 10^{-5}$ FIT/reg	Kopetz, Mitra	↑
Transient (glue logic)	$10^{-7} \div 10^{-9}$ FIT/gate	Kopetz, Mitra	↑

FIT = Failure In Time, number of failures in 10^9 hours



Fault robustness is more and more a top priority concern



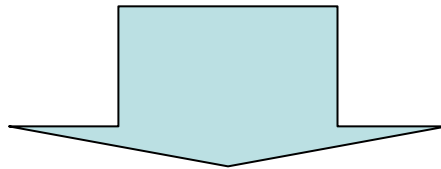
safety-critical automotive applications are looking **today** for next generation solutions and methodologies addressing fault robustness; IEC61508 and in future ISO26262 are more and more popular as reference norms



Background (2)

Modern MCUs:

- Complex CPU with big memories and many peripherals
- Mix of commodity and safety-critical functions
- Complex interconnection scenarios



A comprehensive approach for safety-integrity is needed:

- reducing system costs and complexity
- saving CPU performance
- allowing reuse and flexibility
- easing system 'safety' engineering
- easing system certification



Yogitech faultRobust technology



fRMethodology

A systematic procedure addressing IEC61508 requirements in the design of VLSI components for safety-critical applications

fRIPs

HW modules implementing ad-hoc diagnostic for basic elements like CPU, MEM, BUS and Peripherals aimed to reach appropriate Safety Integrity Level at VLSI component level



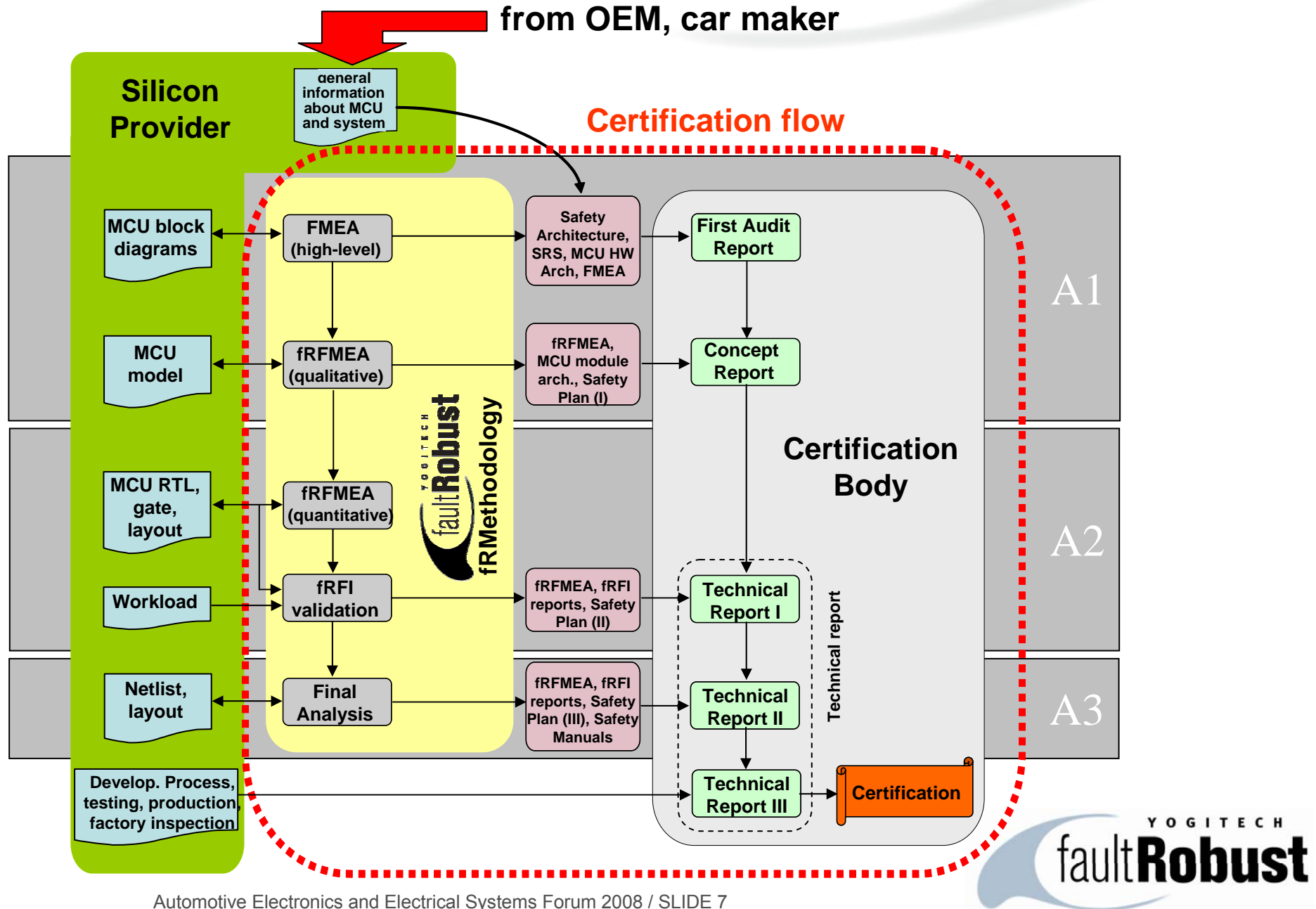
The fRM methodology

- Allowing a safety oriented design exploration at System-on-Chip level (white-box approach)
- Using well established methodologies (FMEA, Fault Injection, etc.) embedded in a standard System-on-Chip design&verification flow
- Computing and validating metrics and parameters required for IEC61508 certification: Safe Failure Fraction, Diagnostic Coverage, Failure Rate and β IC

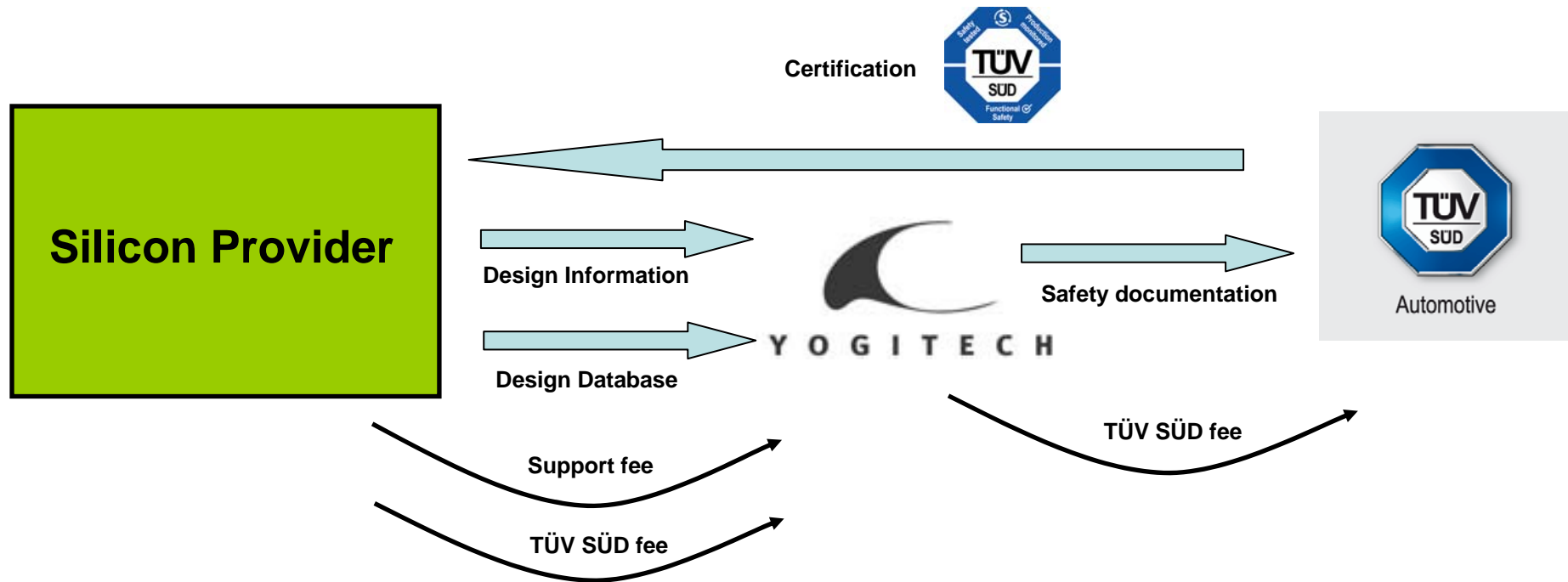
- TÜV SÜD approved



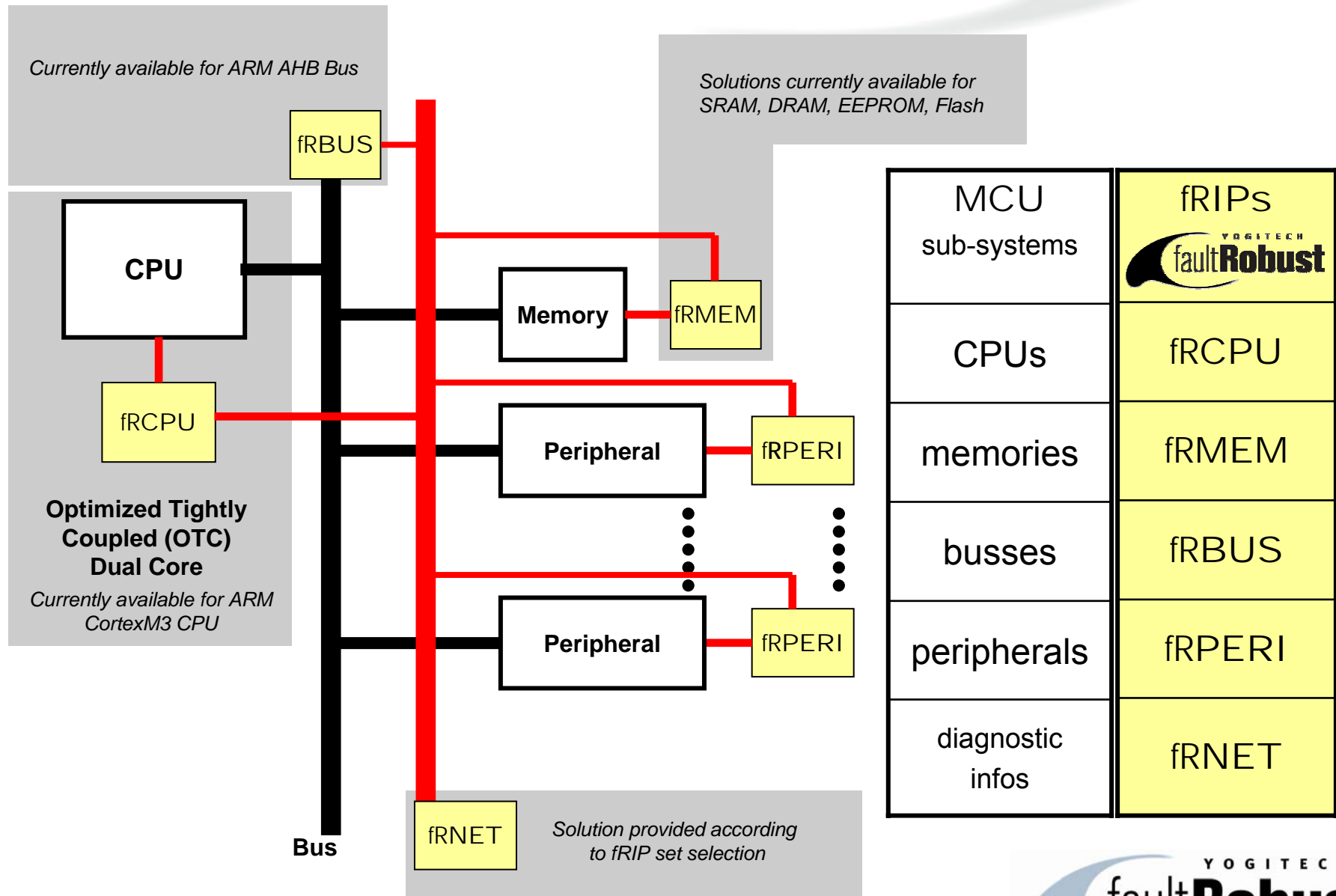
Certifying with fRMMethodology



fRM methodology: Business Model



The faultRobust IPs

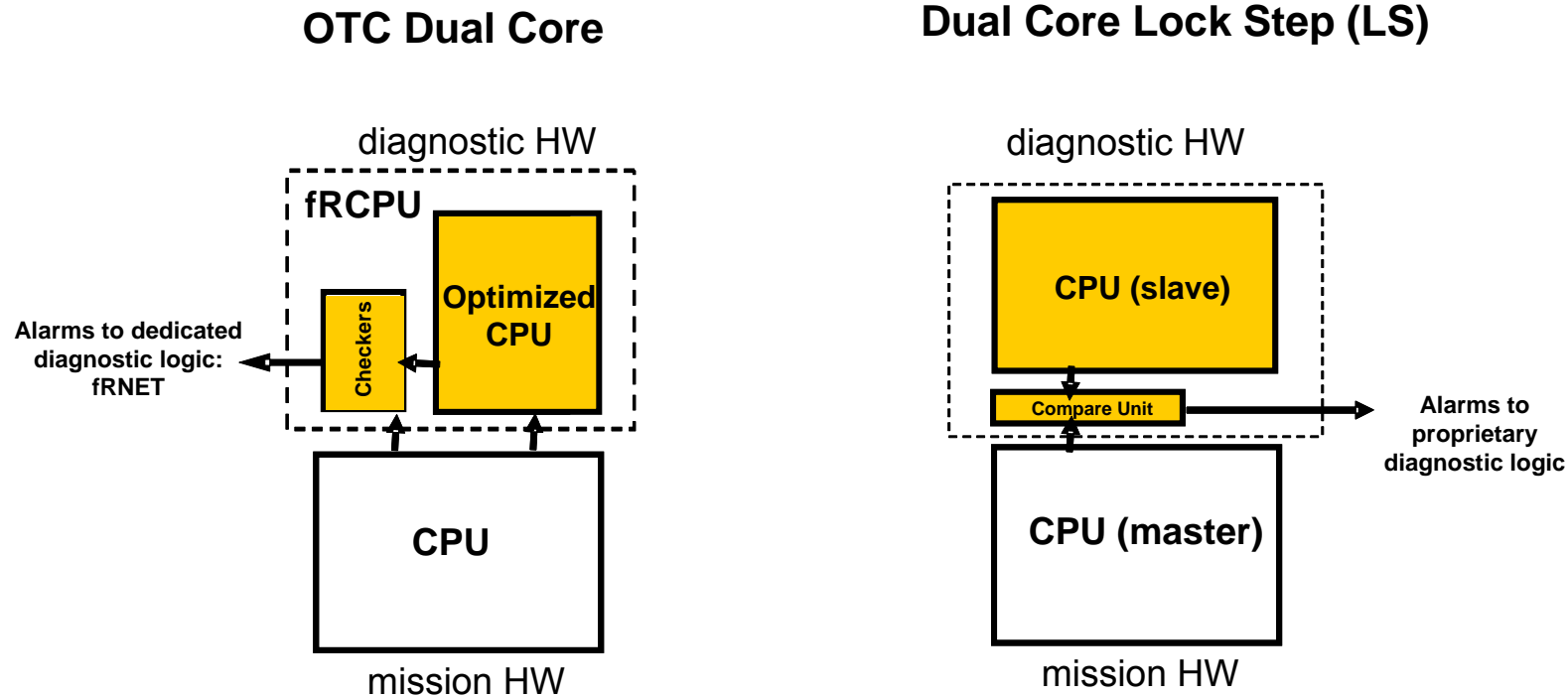


Common features of IPs

- **Architectural + functional diversity**
 - common-cause failures intrinsically reduced
 - $\beta_{IC} \leq 25\%$ achieved without additional layout/HW measures
- **Functional safety guaranteed for the complete subsystem**
 - Safe Failure Fraction calculated at subsystem level
 - Self-checking circuitry included in each fRIP
- **Delivering detailed diagnostic information, e.g.:**
 - type of error
 - load/store fault, register fault, memory bit flip, bus matrix fault
 - context information
 - last instruction executed without errors, address of faulty location, bus slave addressed during the fault, etc...
- **All fRIPs delivered certified by TÜV SÜD**
 - each fRIP is delivered with HW/SW Safety Manuals

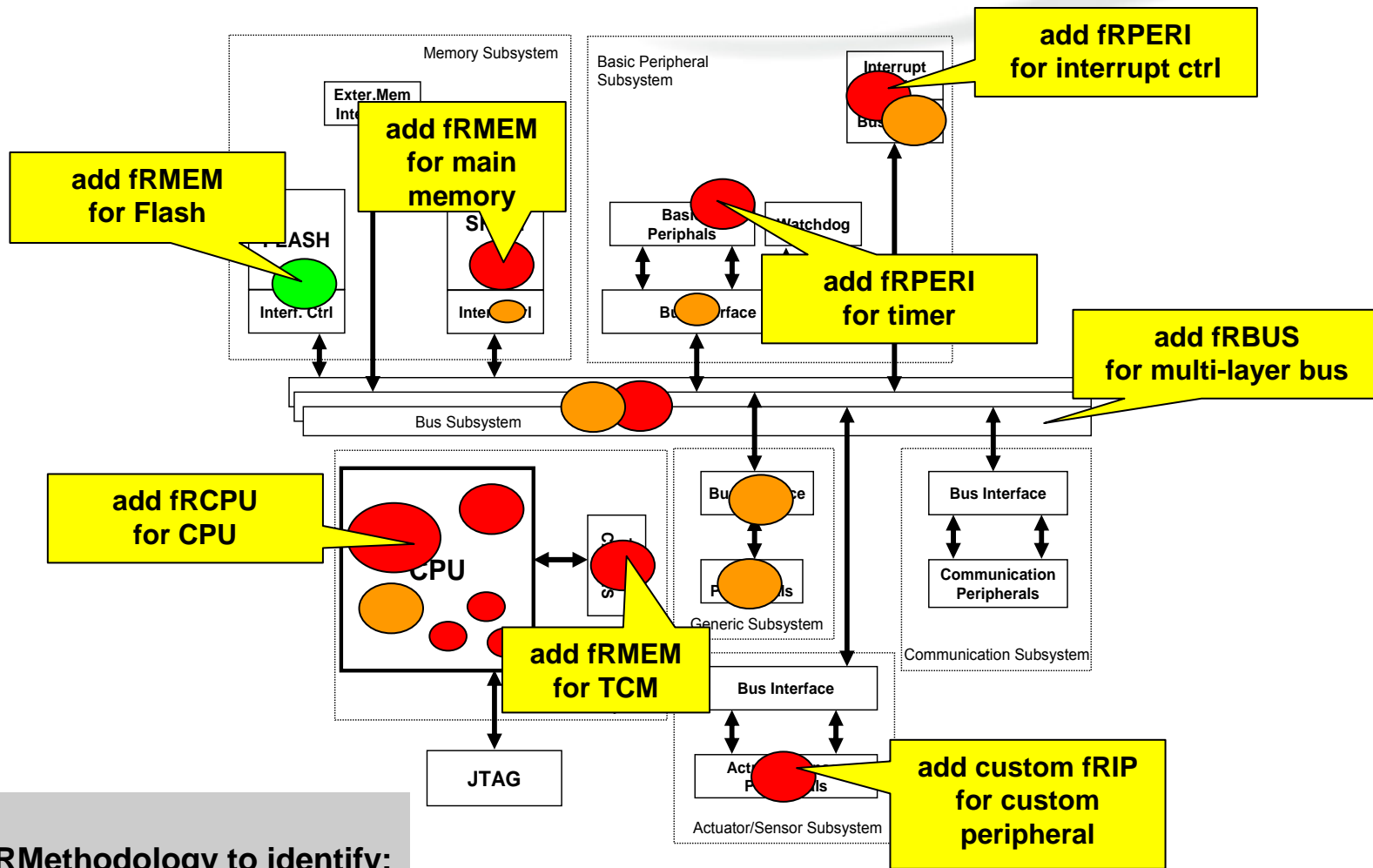


OTC Dual Core block diagram



- OTC dual core's diagnostic cost is 1/5 if compared with LS dual core's diagnostic cost
- OTC dual core requires 85% less SW test if compared with LS dual core

Comprehensive approach



Step 1
applying fRMethodology to identify:

- very critical areas
- critical areas
- attention areas

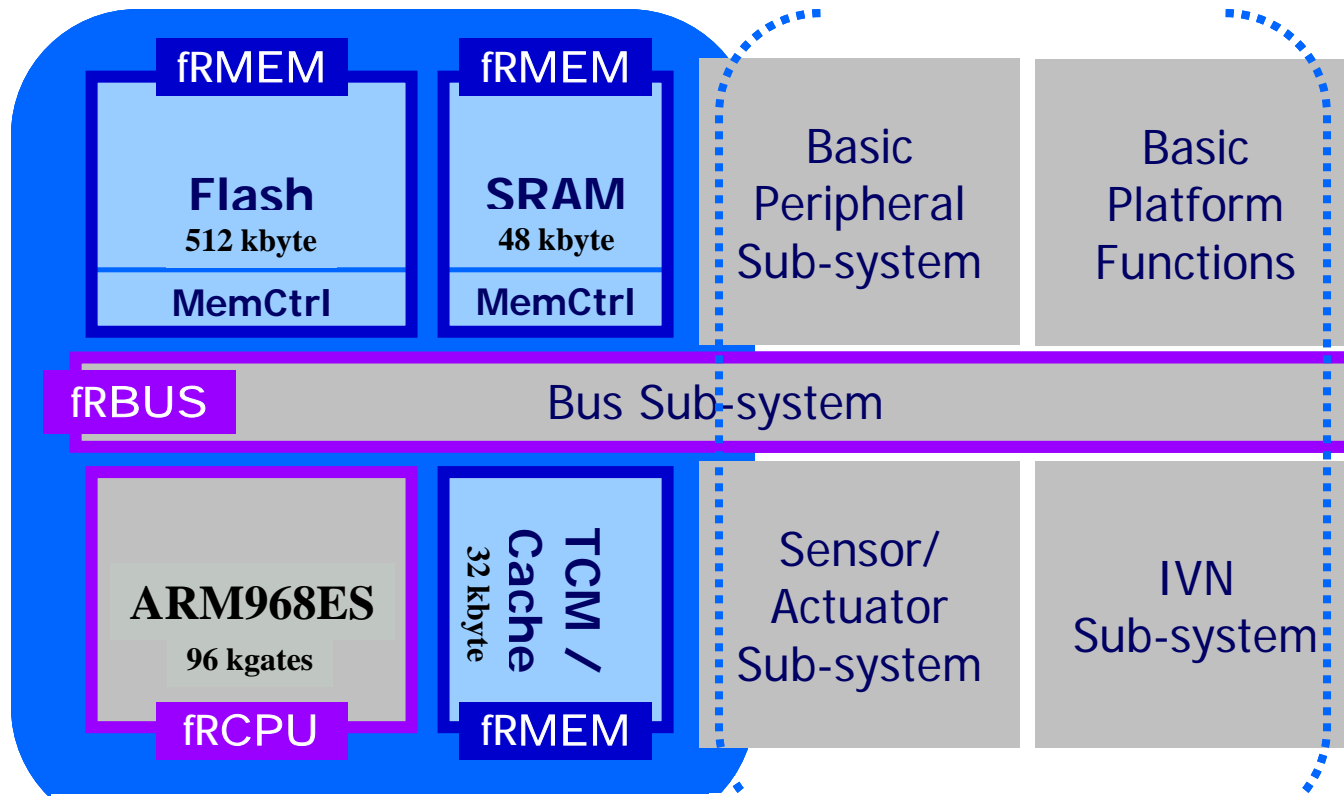
Step 2
implementing ad-hoc diagnostics:

YOGITECH fRIP solutions
...or other solutions



MCU safety concept example

Platform protection approach



Application independent

Safety Integrity Level is achieved independently on the specific application

Application dependent

Safety Integrity Level is achieved with the contribution of specific measures at ECU level (at HW and/or SW level)



**Concept Report
obtained from TÜV
SÜD
by using
fRMethodology**

*"...risk level SIL3
in compliance with
IEC61508
is achievable by the
planned
safety concept..."*



Key advantages areas

Comparison is given with reference to Dual Core LS

MCU level

- **Common-cause failures (CFF) intrinsically reduced**
- **Lower gate counts and easier scalability**
- **Lower power consumption**
- **Lower performance impact**
- **Smaller memory footprint**
- **No risk of undetected systematic HW faults**

ECU level

- **No need for external supervisor/watchdog**
- **Detailed diagnostic available and lower detection latency**
- **Simplified fail operational functionality**
- **Application SW easier to be certified (few CoU)**
- **Shorter MCU time-to-certification**
- **Reduced cost for MCU certification**
- **Fast product derivation (HW certification reusability)**



Conclusions

- **Systematic methodology addressing IEC61508 requirements, easing safety certification.**
 - TÜV SÜD certified white box approach computing and validating metrics required for IEC61508
- **Achieving robustness reducing HW/SW costs**
 - using optimized HW fault supervisors
 - distributing the supervisors to the whole MCU
- **Guaranteeing compliance with IEC 61508**
 - developed under the supervision of TÜV SÜD
 - achieving SIL3
 - Solving β_{IC} (common mode)
- **Being scalable and flexible**
 - implementing a portable and reusable architecture
- **Adding system-level benefits**
 - increasing availability by enhancing diagnostic capability
 - freeing CPU performance
 - allowing system makers to exploit new ideas
 - sophisticated safety concepts
 - next level of component integration



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